

### IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Yoshihiro Yoneda

Serial No.

09/820,470

Filed:

March 29, 2001

For:

SURFACE-MOUNTING SUBSTRATE

STRUCTURE COMPRISING

SUBSTRATE AND PART MOUNTED

ON THE SUBSTRATE

Examiner:

Ishwarbhai B. Patel

Art Unit:

2827

Attny Docket: 082-01

#### **CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being transmitted to the United States Patent and Trademark Office, by being deposited in first class US Mail, with sufficient postage, and addressed to Commissioner for Patents, Washington, DC 20231,

Kim Gubitosi Dated: April 16, 2003

### **COVER LETTER**

Commissioner for Patents Washington, DC 20231

Sir:

Submitted are the following documents:

- 1) This cover letter;
- 2) Supplemental IDS Statement w/Form 1449, and References (17 pages); and
- 3) Post card return receipt.

No additional fees are believed to be required. In the event that an additional fee is required with respect to this communication, the Commissioner is hereby authorized to charge any additional fees, or credit any overpayment, to Paul & Paul Deposit Account No. 16-0750.

Date: April 16, 2003

XXX

Respectfully/Submitted,

John J. Simkanich Regis. No. 26,036

Paul & Paul

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Philadelphia, PA 19103

(215) 568-4900 (FAX) 215-657-5057

Order No. /

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Serial Number:

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Inventor:

Yoshihiro Yoneda

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# SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT WITH FORM 1449

Commissioner for Patents Washington, DC 20231

Sir:

Applicants request consideration of the following information disclosure statement, pursuant to 37 CFR 1.97(e)(1) and 1.97(c)(1). No final action has been mailed under Sec. 1.113, no notice of allowance has been issued under Sec. 1.311. No information contained in the IDS was cited in a communication from a foreign patent office in a counterpart foreign application, and, to the knowledge, information and belief of the undersigned, upon reasonable inquiry, no item in the IDS was known to any individual designated in §1.56(c) more than 3 months prior to the date of this IDS.

Submitted herewith is a PTO Form 1449. Also submitted are copies of:

- 1. JP9223715, (1997, Aug 26), Watanabe Masaki, for CONNECTING STRUCTURE OF FLIP CHIP OR FLIP CHIP CARRIER;
- 2. JP10013003, (1998, Jan 16), Kishigami Masamitsu, for SEMICONDUCTOR DEVICE;

# Remarks on Relevancy

All documents above-listed are submitted in Japanese with an English abstract. The requirements specified by MPEP 609A(3) and 37 CFR 1.98 are considered to have been satisfied.

Date: April 16, 2003

Respectfully submitted,

by:

Jehn J. Simkanich Regis. No. 26,036

2900 Two Thousand Market Street

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## **CERTIFICATE OF MAILING**

Commissioner for Patents Washington, D.C. 20231

I hereby certify that this correspondence is being deposited in the United States Postal Service with sufficient postage as first class mail in an envelope addressed to:

PAUL & PAUL by: John J. Smkanich

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